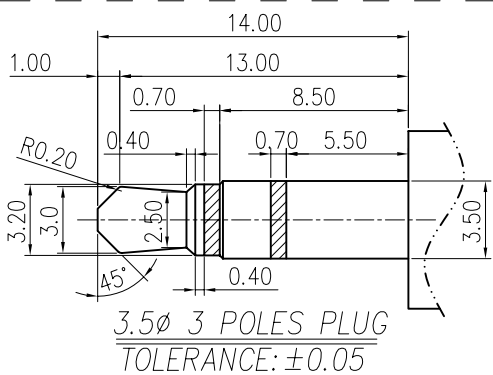
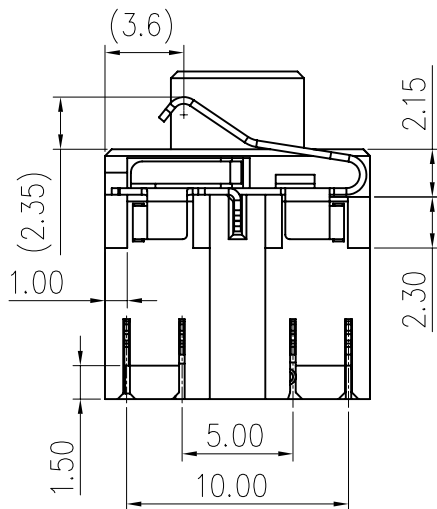
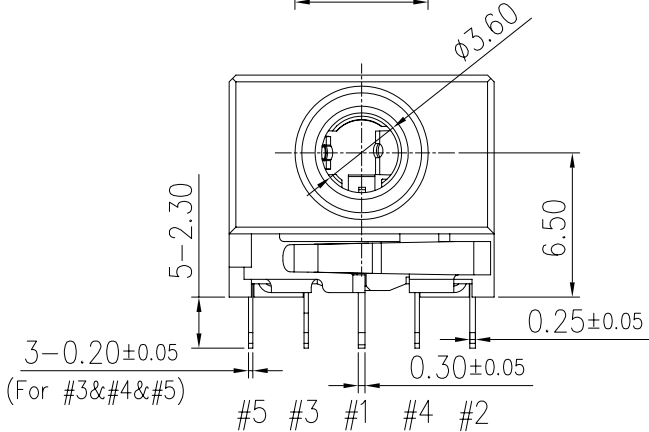
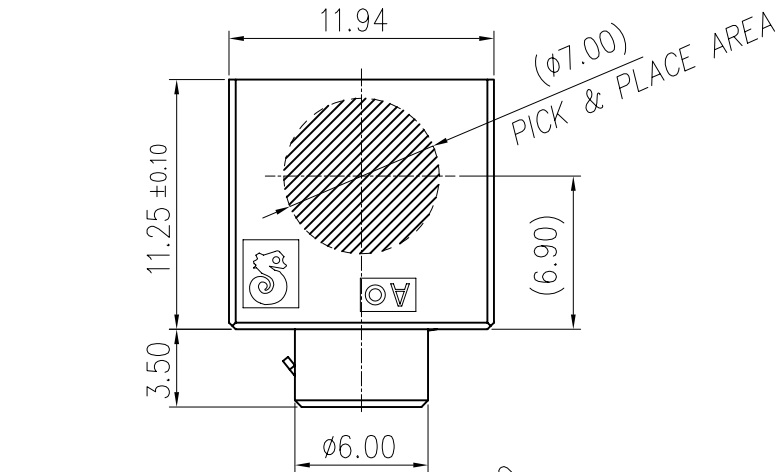
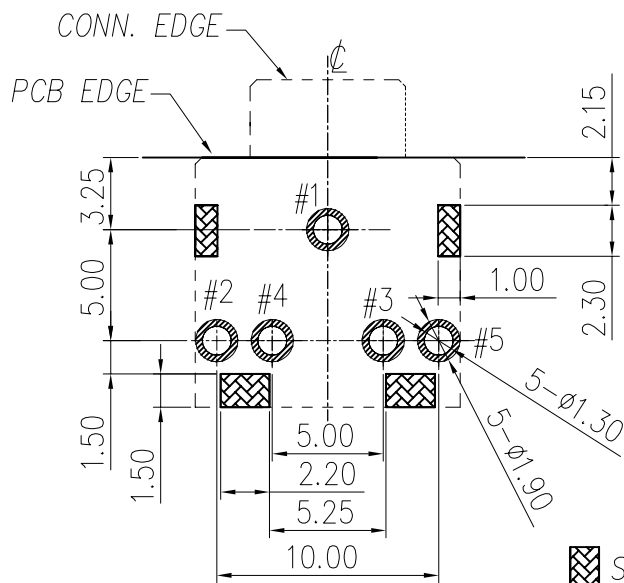
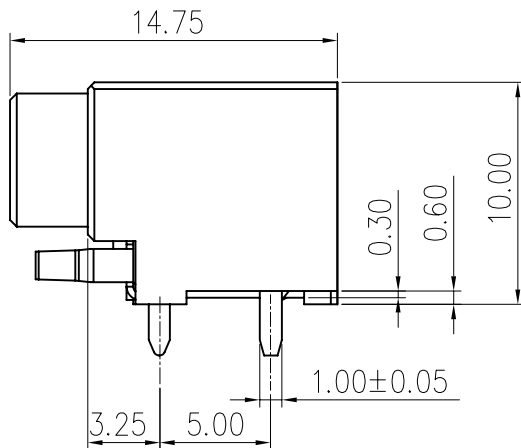
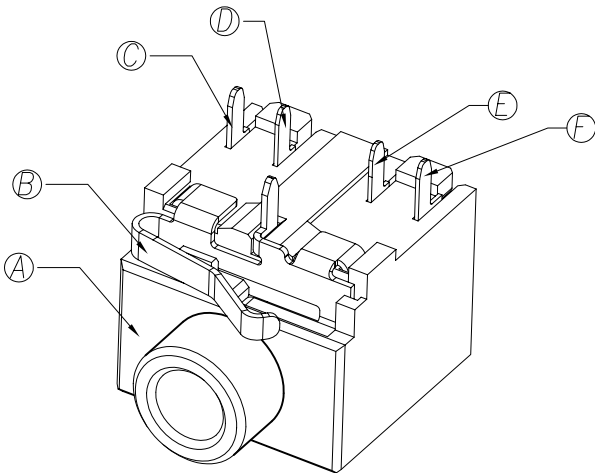
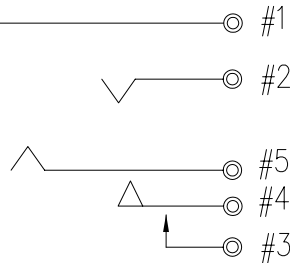


REV.	ECN NO OR DESCRIPTION	REVISED	DATE
A	PRODUCT RELEASE	WZJ_WEI	2016.12.16



SCHEMATIC



RECOMMENDED P.C.B. LAYOUT
TOP VIEW (TOLRANCE: ±0.05)

- ELECTRICAL CHARACTERISTICS:
 - CURRENT RATING: 1 AMPERE PER CONTACT.
 - CONTACT RESISTANCE: 50mΩ MAX.
 - DIELECTRIC WITHSTANDING VOLTAGE: 500V AC FOR ONE MINUTE.
 - INSULATION RESISTANCE: 100MΩ MIN. MEASURED BY 500 VDC
- MECHANICAL CHARACTERISTICS:
 - INSERTION FORCE : 0.4~3.0 KGF
 - WITHDRAWAL FORCE : 0.3~3.0 KGF
- LIFE TEST: 5,000 CYCLES.
- OTHER GENERAL SPEC. TO REFER "2SJ2364 SERIES SPEC".
- TO CONFORM TO THE SINGATRON HAZARDOUS SUBSTANCE FREE SPEC.
- HALOGEN FREE PRODUCT IDENTIFICATION MARK ON JACK: ©
- HALOGEN FREE PRODUCT IDENTIFICATION LABEL ON PACKAGING:
- FOR REFLOW SOLDERING LEAD-FREE PROCESS.
- PACKAGING: TAPE & REEL.

F	RING	1	COPPER ALLOY 0.2T	Au 30u" ON CONTACT AREA AND GOLD FLASH ON SOLDER TAIL AREA, Ni ALL OVER PLATING
E	MAKE TERMINAL	1	COPPER ALLOY 0.2T	
D	TRANSFER	1	COPPER ALLOY 0.2T	
C	TIP	1	COPPER ALLOY 0.25T	
B	EARTH	1	COPPER ALLOY 0.3T	GOLD FLASH OVER Ni PLATING
A	BODY	1	HIGH TEMP. THEROPLASTIC UL 94V-0	PINK(701C)
NO	DESCRIPTION	QTY	MATERIAL	PLATING & COLOR
UNLESS OTHERWISE SPECIFIED TOLERANCES		 Singatron Enterprise Co., Ltd. 信音企業股份有限公司		
DECIMALS: ANGLES:		TITLE	3.5ø PHONE JACK	
X :±0.5	X :±2°	DWN	PART NO. 2SJ2364-000131F	
X.X :±0.3	X.X :±1°	CHKD	SCALE 3:1 UNIT: mm 	
X.XX :±0.2		APVD	SIZE: A3	SHEET: 10F1
		REV: A		
CUSTOMER COPY				